

Service Manual S68 Level 1-3



| Release Date | | Department | Notes to change |
|--------------------|--|----------------------|-----------------|
| R 1.0 22.02.2006 B | | BenQ Mobile S CC CES | New document |
| | | | |
| | | | |

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1 Key Feature

| Otan dand Oraștiana | Tri-band GSM 900/1800/1900 | | |
|--------------------------------|---|--|--|
| Standard Systems | EGSM (GSM phase 2/phase 2+) | | |
| | GPRS class 10 | | |
| | Vocoders FR, HR, EFR, AMR | | |
| Stand-by Time | Up to 300 h (standard battery) | | |
| Talk Time | Up to 300 min (standard battery) | | |
| Battery Technology | Battery: Li-lon 660 mAh | | |
| Battery Capacity | Charging time: Less than 2 h for 100% | | |
| Weight | 78,5 g | | |
| Volume | 44 cm ³ | | |
| Length | 107 mm | | |
| Width | 46 mm | | |
| Thickness | 13,2 mm | | |
| Storage | 8 MB user memory | | |
| SIM Functionality / | SIM Application Toolkit (class 3) | | |
| Security Controls | SIM lock, various levels | | |
| | PIN 1 & 2 control | | |
| | Ciphering A5.1, A5.2 and A5.3 | | |
| Antenna | SIM plug-in (3/1.8 V), SAT class 3 Integrated | | |
| | | | |
| Data Services | Mobile Internet access (WAP 1.2.1 plus parts of 2.0) Data download OTA via SMS or WAP | | |
| | MMS release 98 | | |
| | EMS rel. 4.3 | | |
| | Data services (CSD) at 9.6 Kbps and GPRS | | |
| | (up to 53.6 Kbps) | | |
| B: 1 /B: 1 ··· · | E-mail client | | |
| Display / Display Illumination | 132 x 176 pixels, 262,144 colors, enhanced TFT, transflective, high-end flat PMMA | | |
| | window | | |
| Camera | n/a | | |
| Connectivity | USB cable / Bluetooth® | | |
| Features | Basic organizer (including day, week, and month) with | | |
| | Outlook® and Lotus Notes® synchronization, PIM | | |
| | SMS, voice messaging (via MMS) EMS and MMS, e-mail client | | |
| | Pop3 | | |
| | MMS supporting text, still images, voice and animations | | |
| | SyncML 1.2.1 (or higher via OBEX and OTA) Handsfree operation | | |
| | Dual-speaker system for outstanding sound quality | | |
| | 64-chord polyphonic ringtones, MIDI | | |
| | Very slim appearance | | |
| | Real metal keypad and housing (brushed aluminum) | | |
| | WAP 2.0 stack | | |
| | Java MIDP 2.x Wide range of headset and car kit solutions with Bluetooth® | | |
| | Wide range of headset and car kit solutions with Bluetooth® technology | | |
| | юонноюду | | |

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2 S68 Interface to Accessories

Original Accessories

Fashion & Carry

Leather Case FCL-720

Energy

- Li-Ion Battery 660 mAh EBA-120
- Travel Charger (EU & UK) ETC-100/110
- Car Charger Plus ECC-100
- Desk Top Stand EDS-100

Handsfree Portable

- Headset Basic HHS-100
- Headset HHS-110
- Headset Purestyle HHS-120
- Headset Bluetooth® HHB-100
- Headset Bluetooth® Clip HHB-130/131
- Headset Bluetooth® Comfort HHB-160/161
- Headset Bluetooth® HHB-700/710
- Charger Adapter ECA-500 (for HS BT HHB-700/710)
- Charger Adapter ECA-100 (for HS BT HHB-130/131/160/161)

Car Solutions

- Car Kit Bluetooth® Easy HKW-100
- Car Kit Bluetooth® Portable HKW-700
- Car Kit Bluetooth® HKW-710 (successor of HKW-600)
- Car Kit Bluetooth® SIM HKW-720
- Car Kit Portable HKP-100
- Mobile Holder HMH-100

Office

- Data Cable DCA-100 (RS232)
- Data Cable USB DCA-140
- Sync Station DSC-100



3 Unit Description of S68

Highly attractive premium design: very slim phone (13 mm) with real metal (brushed aluminum) surface and keypad.

Focusing on the core and most convenient business functions, PIM, Bluetooth®, Fax and Document Viewer, and other business applications that enrich professional life.

New simplified and intuitive menu structure.

Fast Dialing™ key, voice messaging (via MMS), dictaphone, and e-mail client.

Excellent overall ergonomics.

Superb sound quality (including handsfree talking).

Optimal visibility of content display under all lighting conditions.



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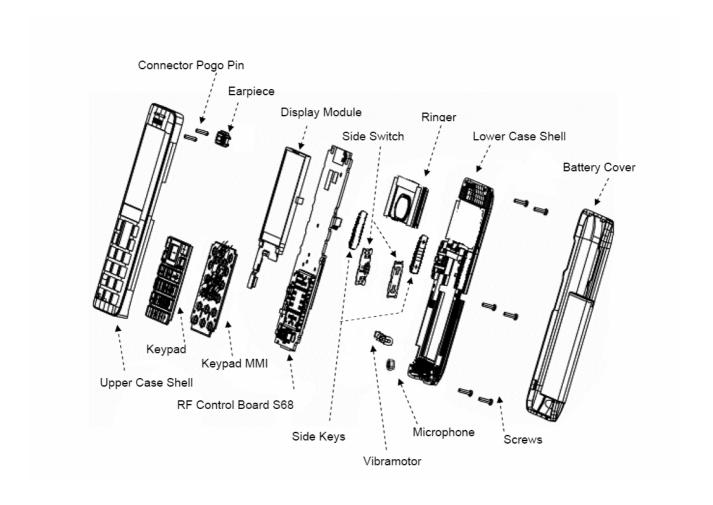
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4 Exploded View of S68



Without illustration:

Shielding Cover RF Shielding Cover BB Top Shielding Cover BB BOT Shielding Cover BT



Disassembly of S68

All repairs as well as disassembling and assembling have to be carried out in an ESD protected environment and with ESD protected equipment/tools. For all activities the international ESD regulations have to be considered.

For more details please check information in c – market

https://market.bengmobile.com/SO/welcome.lookup.asp

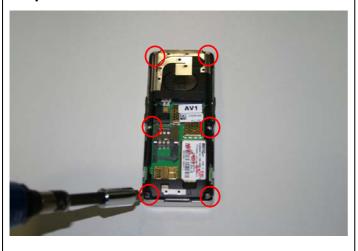
There you can find the document "ESD Guideline".

Step 1



Remove Battery Cover and Battery.

Step 2



Remove screws with the Torque – Screwdriver.

T5+

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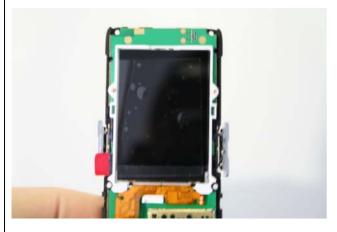


Disassemble Upper Case from Lower Case.

Step 4



Step 5



To avoid scratches, it is mandatory to place a protection foil onto the display!

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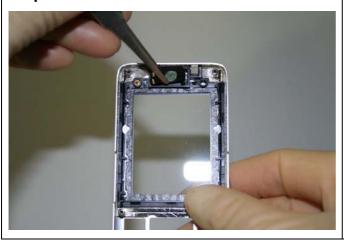
Remove Keypad MMI by using Tweezers carefully.

Step 7



Remove Keypad by using Tweezers carefully.

Step 8



Use Tweezers to remove Earpiece.

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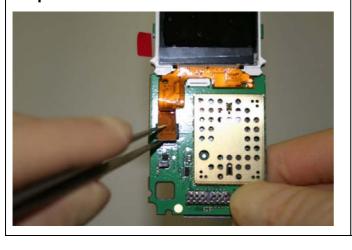


.Remove PCB from Lower Case.

Step 10



Step 11



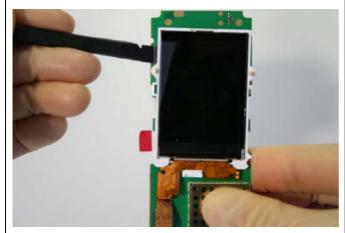
Disconnect Flex Cable from PCB socket by using Tweezers.

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Loosen Display Module from PCB with Alternative Opening Tool.

Step 13



Step 14

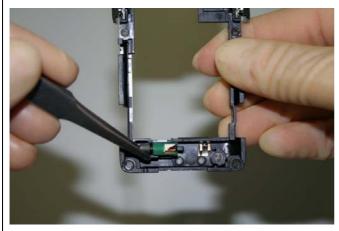


Remove Ringer.

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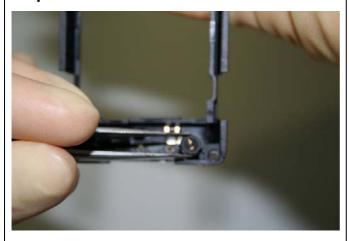
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Remove Vibramotor by using Tweezers.

Step 16



Use Tweezers to remove Microphone.

Step 17



Use Tweezers to remove Side Keys and Side Keys MMI.

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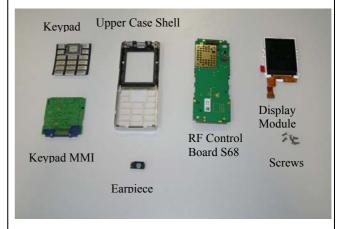




Overview Lower Parts



Overview Upper Parts





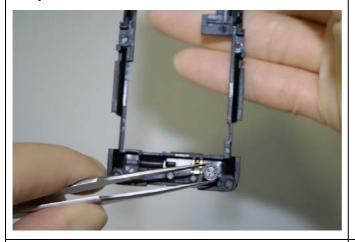
6 Assembly of S68

Step 1



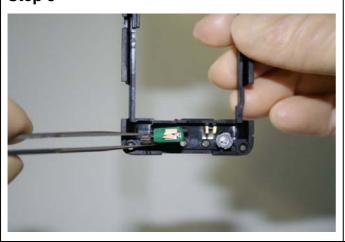
Assemble Ringer by using Tweezers.

Step 2



Assemble Microphone by using Tweezers

Step 3



Assemble Vibramotor by using Tweezers.

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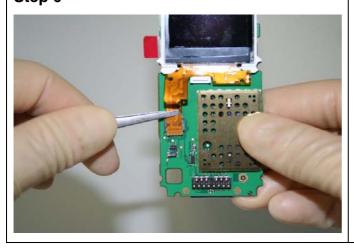
Assemble Side Keys and Side Keys MMI

Step 5



Assemble Display Module on PCB.

Step 6



Connect Flex Cable with PCB socket.

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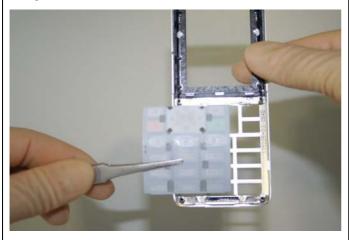
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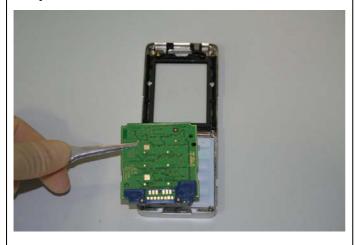


Step 7



Assemble Keypad.

Step 8



Assemble Keypad MMI.

Step 9



Assemble Earpiece.

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Attention! Before assembling the Display

Module it is mandatory to remove the

Display Foil!

Step 11



Place PCB with assembled Display in the Upper Case.

Step 12



Assemble Lower Case onto the Upper Case.

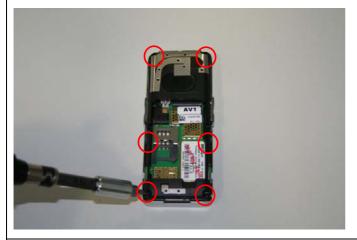
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Place screws with the Torque – Screwdriver.

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Step 14



Assemble Battery.

Step 15



Assemble Battery Cover.

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7 BenQ Service Equipment User Manual

Introduction

Every LSO repairing BenQ handset must ensure that the quality standards are observed. BenQ has developed an automatic testing system that will perform all necessary measurements. This testing system is known as:

BenQ Mobile Service Equipment

• For disassembling / assembling

| Torque – Screwdriver Part Number: F 30032 – P 228 – A1 |
|---|
| Opening tool (Case opening without destroying) Part Number: F 30032 – P 38 – A1 |
| Alternative Opening tool Part Number: F30032 – P583 – A1 |
| Tweezers |

For testing

All mobile phones have to be tested with the GRT – Software. The service partner is responsible to ensure that all required hardware is available.

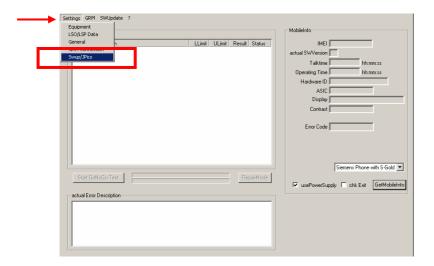
For additional Software and Hardware options as well as the supported GRT equipment, please check the GRT User manual.

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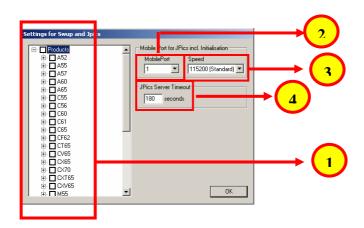
8 GRT Software: Functionality Configuration

Sep 1: Select "Settings >> SWUP / JPICS"



Step 2: Proceed as follows:

- Select all required Variants you need to repair (click onto the "+" in front of the product name.
- Check Com-Port setting. If necessary change it
- Check speed setting. Select always the lowest speed if your PC does not have a fast serial card
- Enter the value for "JPICS Server Timeout". Be careful, this value defines how long GRT tries to reach the server until you get an error message. Do not select a very long time



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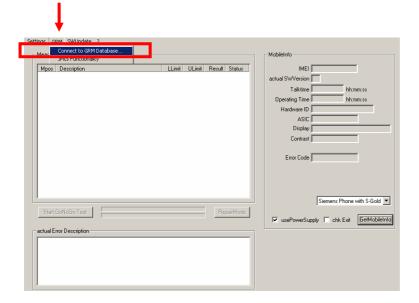
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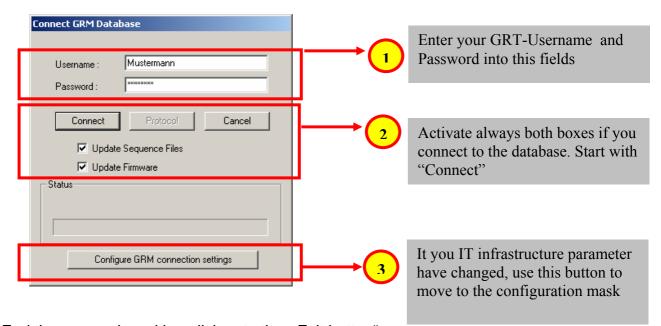
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Step 3: Connect to GRM Server

Choose in the section "GRM" the "Connect to GRM Database" functionality





 End the connection with a click onto the "Exit button" (appearing after successful data exchange)

GRT Software has now finished all required settings and configuration tasks. All files have been down- and uploaded.

In dependency of the selected number of mobile phones and variants the volume of transferred date could be (~100MB)

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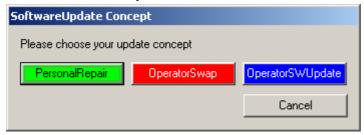


9 GRT Software: Regular Usage

Step 1: Select the section SWUpdate



Step 2: Choose the area you want to work with



Personal Repair

Personal Repair is always accessible. Basis for the decision if a SW-Update is authorised by Siemens is the so called <u>Service Release-Table</u>.

Example: Mobile Phone has already SW50. <u>Service -Release-Table</u> shows SW50

In this case SW-Update is not necessary and therefore not authorised

In any case customer data can be erased on request. (xfs and mapping have to be activated) Of course **JPICS** hardware and authorisation have to be available.

Operator SWAP

This area is only accessible if you are released by the service management to perform SW-Updates for Net-Operators. Basis for the decision if a SW-Update is authorised by Siemens is the so called <u>Master-Table</u>.

Customer data will be erased without any exception and any chance to influence by the user. **JPICS** hardware and authorisation have to be available.

Operator SWUpdate

This area is only accessible if you are released by the service management to perform SW-Updates for Net-Operators. Basis for the decision if a SW-Update is authorised by Siemens is the so called Master-Table.

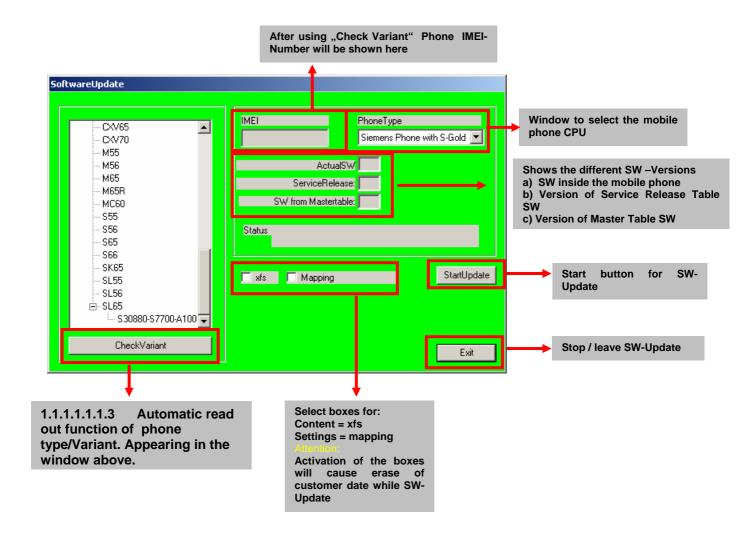
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Like in "Personal Repair" customer data can be erased on request. (xfs and mapping have to be activated) Of course **JPICS** hardware and authorisation have to be available.

9.1 Window explanation

This general explanation is valid for all SW-Update channels (Personal Repair, Operator SWAP, Operator SWUpdate)



Remarks:

In case of malfunction please check

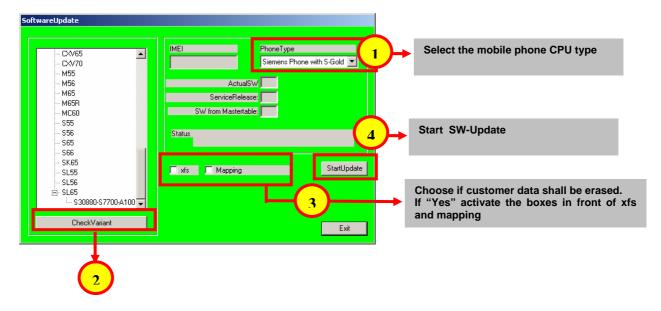
- Is the correct phone type selected
- Is the correct COM-Port selected
- If a variant is missing, move back to Settings select the missing variant and conncet the GRM Server. Then continue with SW-Update.

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9.2 Case 1: Personal Repair (green)

Step 1: Carry out step 1 – 4 to start SW-Update.



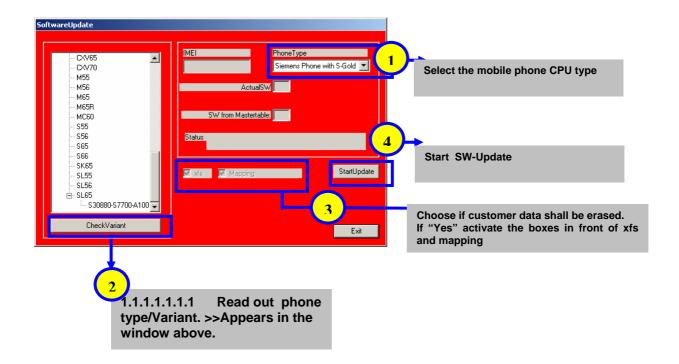
Remarks:

- The decision about a Siemens authorised SW-Update depends only on the Service Release-Table.
- The SW which is booted by GRT can be below the SW mentioned in the Service Release Table, if this SW is not released for the Net-Operator
- If **xfs** and **mapping** are activated, GRT will erase in any case the customer data even if the action is cancelled.
- If the user wants to download an other variant then the automatically identified one, he has simply to select an other variant from the list. Afterwards he has to start the SW-Update



9.3 Case 2: Operator SWAP (red)

Step 1: Carry out step 1 – 4 to start SW-Update.



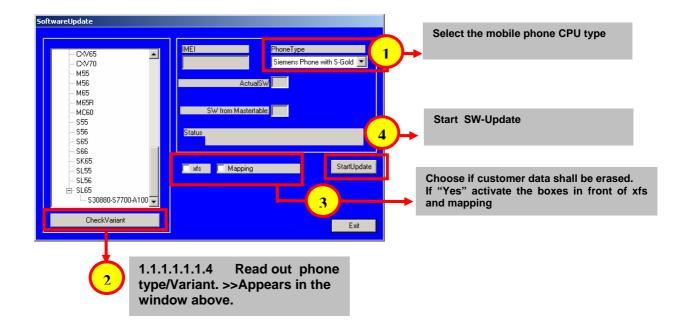
Remarks:

- The decision about a Siemens authorised SW-Update depends only on the Master-Table .
- The user has no chance to influence the decision
- **Xfs** and **mapping** are always activated there is no chance to deactivate them. GRT will erase in any case the customer data even if the action is cancelled.
- If the user wants to download an other variant then the automatically identified one, he has simply to select an other variant from the list. Afterwards he has to start the SW-Update



9.4 Case 3 Operator SWUPdate (blue)

Step 1: Carry out step 1 – 4 to start SW-Update.

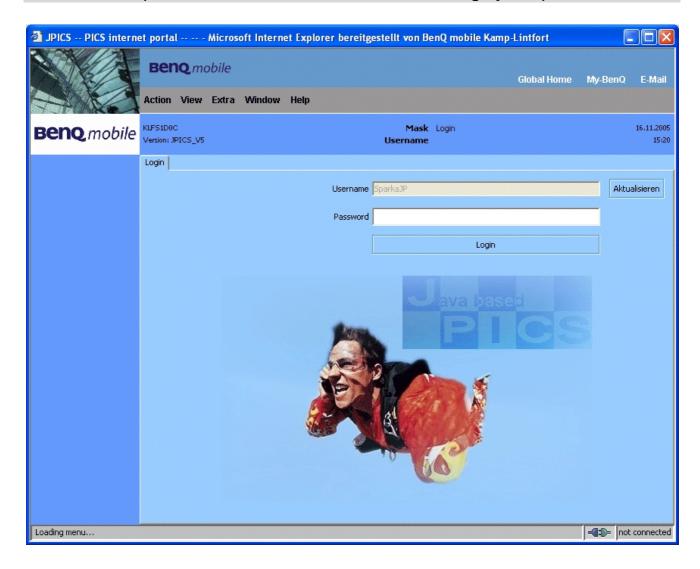


Remarks:

- The decision about a Siemens authorised SW-Update depends only on the Master-Table.
- The user has no chance to influence the decision
- Xfs and mapping can be activated on demand. GRT will erase in any case the customer data even if the action is cancelled.
- If the user wants to download an other variant then the automatically identified one, he has simply to select an other variant from the list. Afterwards he has to start the SW-Update



10 JPICS (Java based Product Information Controlling System)



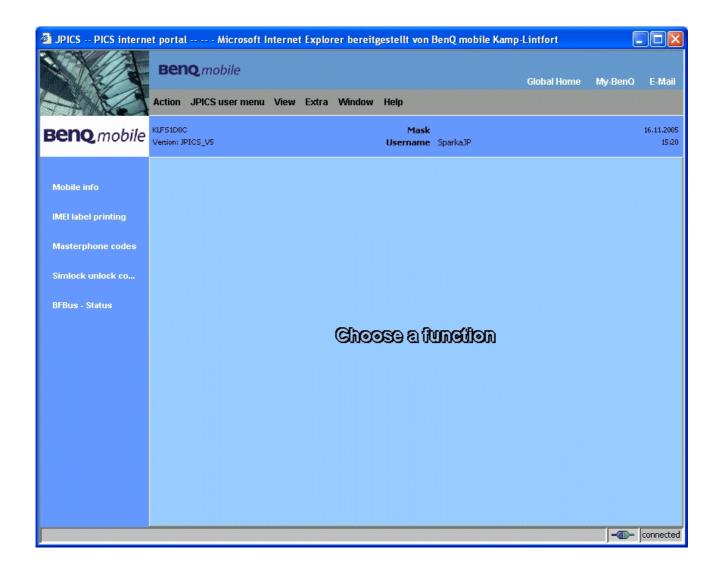
10.1. Overview

The following functions are available for the LSO:

- General mobile information
- Generate PINCODE
- Generate SIMLOCK UNLOCK Code
- Print IMEI labels
- Lock, Unlock and Test the BF Bus

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The access to the JPICS server which is located in Kamp – Lintfort is protected by chip card and in addition using secure socket layer (SSL) connection.

The JPICS server is only available for authorized users with a specially coded smart card. These smart cards and the administration of the JPICS web server and the PICS database

server can only be provided by the JPICS – TRUST – Center of the <u>responsible</u>
 department in Kamp – Lintfort.

In case of any questions or requests concerning smart cards or administration of the databases please ask your responsible BenQ Customer Care Manager.

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10.2. Installation overview

The following installation description assumes that a web browser is already installed. JPICS is tested with the following browsers:

- 1. Internet Explorer Version 5.5 and higher
- 2. Netscape Version 6 and higher

For further information regarding supported browsers, browser version and supported operating systems, see the <u>Sun FAQ's</u>.

Here is a step by step instruction to install all the required components:

It is necessary to follow this order!

- 1. Smart Card Reader (Omnikey: Cardman 2020 USB or Cardman 3121 USB)
- 2. CardOS interface (Siemens Version 3.0 B)
- 3. Java Runtime Environment (Sun)
- 4. Java additional components

Every user is responsible for a proper installation matching the license agreements.

For installation and further access you need the following:

- 1. The JPICS Installation CD
- 2. The Smart Card JPICS. These cards can be ordered via your responsible Customer Care Manager within Siemens or on http://jpics.siemens.com/jpics/admin/request-new_ipics.jsp
- 3. A supported Smart Card Reader (Omnikey Cardman) in order to access your Smart Card.

<u>Remark:</u> We recommend using Cardman 2020 USB or Cardman 3121 USB. Serial card readers are not supported!!

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10.3. Generate Codes

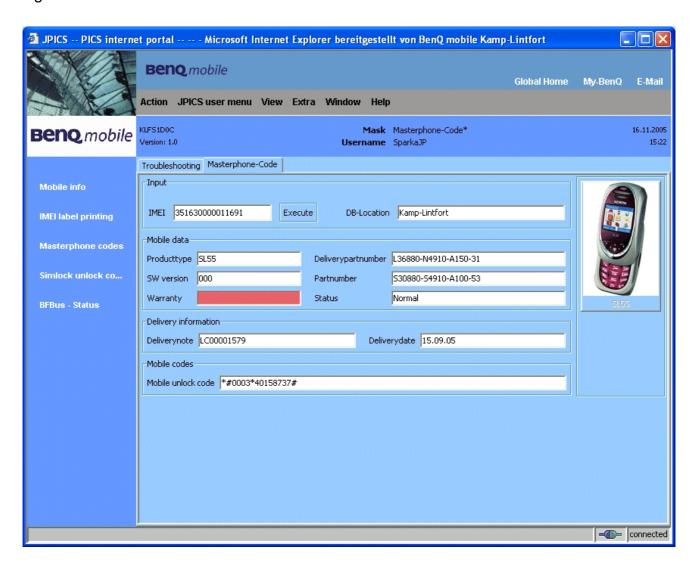
In the JPICS application you can choose to generate:

- Masterphone codes
- Simlock Unlock Codes

Masterphone codes

The **Masterphone code** is used to unlock blocked mobiles.

Masterphone codes can only be supplied for mobiles which have been delivered in a regular manner.



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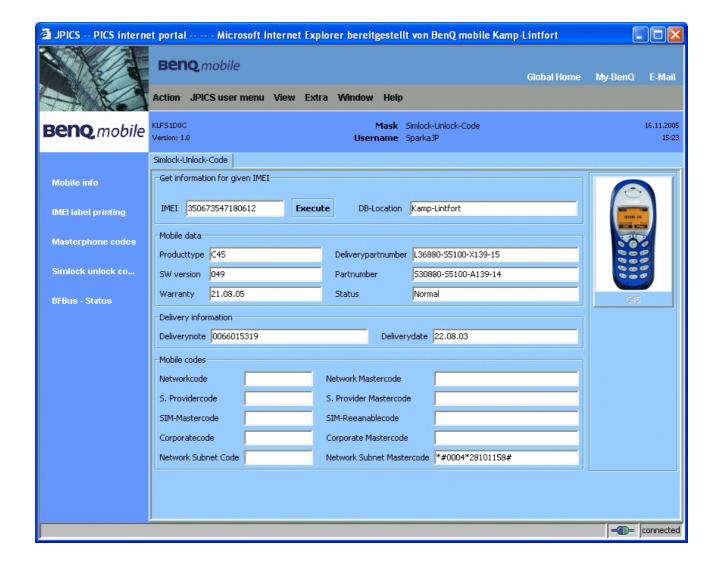
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Simlock - Unlock - Code

The **Simlock – Unlock – Codes** can only be generated if the following conditions are given:

- Mobile must have an active Simlock inside.
- The user must be given the authorization to obtain Simlock Unlock Codes for the variant of the operator to which the mobile was delivered last time.



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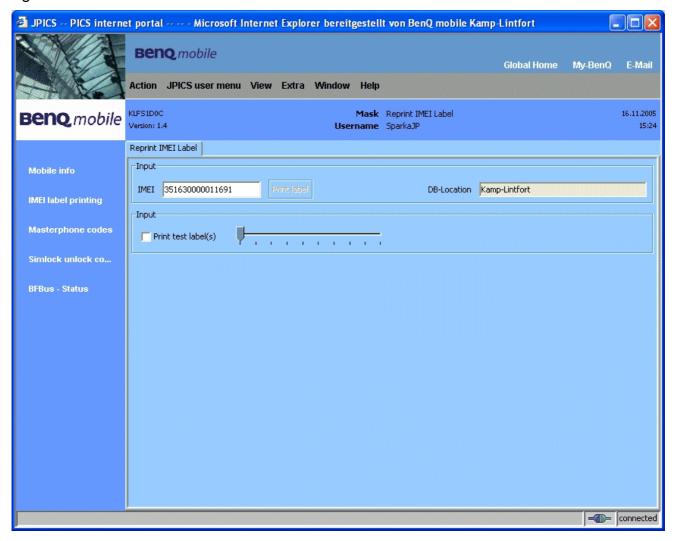
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10.4. Printing IMEI label

The module "printing IMEI label" offers the possibility to re-print IMEI labels for mobiles again.



You are able to print 1 label in just one step.

To prevent that misaligned labels are being printed, the setting "Print test labels = \checkmark " is activated by default. After having printed a well aligned test label you can uncheck the setting and print the correct label.

Hint:

For correct printing of IMEI labels you must have a **Zebra – label printer** with special material that fits for label printing. This printer has to be connected to local LPT1 printer port (also see Installation of IMPRINT) and MUST feature a printing resolution of 300dpi.

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11 International Mobile Equipment Identity, IMEI

The mobile equipment is uniquely identified by the International Mobile Equipment Identity, IMEI, which consists of 15 digits. Type approval granted to a type of mobile is allocated 6 digits. The final assembly code is used to identify the final assembly plant and is assigned with 2 digits. 6 digits have been allocated for the equipment serial number for manufacturer and the last digit is spare.

The part number for the S68 is S30880-S1150-#xxx where the last for letters specify the housing and software variant.

S68 series IMEI label is accessible by removing the battery.

Re – use of IMEI label is possible by using a hair – dryer to remove the IMEI label.

On this IMEI label, BenQ has also includes the data code for production or service, which conforms to the industrial standard DIN EN 60062. The data code comprises of 2 characters: first character denotes the **year** and the second character denotes the **month**.

For example: \$5

| CODE | Year | Month | CODE |
|------|------|-------|------|
| Р | 2002 | MARCH | 3 |
| R | 2003 | APRIL | 4 |
| S | 2004 | MAY | 5 |
| Т | 2005 | JUNE | 6 |
| U | 2006 | JULY | 7 |

To display the IMEI number, exit code and SW/HW version, key: * # 0 6 #

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12 General Testing Information

General Information

The technical instruction for testing GSM mobile phones is to ensure the best repair quality.

Validity

This procedure is to apply for all from Siemens AG authorized level 2 up to 2.5e workshops.

Procedure

All following checks and measurements have to be carried out in an ESD protected environment and with ESD protected equipment/tools. For all activities the international ESD regulations have to be considered.

Get delivery:

- > Ensure that every required information like fault description, customer data a.s.o. is available.
- > Ensure that the packing of the defective items is according to packing requirements.
- ➤ Ensure that there is a description available, how to unpack the defective items and what to do with them.

Enter data into your database:

(Depends on your application system)

- ➤ Ensure that every data, which is required for the IRIS-Reporting is available in your database.
- Ensure that there is a description available for the employees how to enter the data.

Incoming check and check after assembling:

!! Verify the customers fault description!!

- After a successful verification pass the defective item to the responsible troubleshooting group.
- ➤ If the fault description can not be verified, perform additional tests to save time and to improve repair quality.

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- Switch on the device and enter PIN code if necessary unblock phone.
- Check the <u>function</u> of all **keys** including **side keys**.
- Check the **display** for error in <u>line and row</u>, and for <u>illumination</u>.
- Check the **ringer/loudspeaker** acoustics by individual validation.
- Perform a **GSM Test** as described on page 36.

Check the storage capability:

- Check internal resistance and capacity of the battery.
- Check battery charging capability of the mobile phone.
- Check charging capability of the power supply.
- Check current consumption of the mobile phone in different mode.

Visual inspection:

- > Check the entire board for liquid damages.
- Check the entire board for electrical damages.
- Check the housing of the mobile phone for damages.

SW update:

Carry out a software update and data reset according to the master tables and operator/customer requirements.

Repairs:

The disassembling as well as the assembling of a mobile phone has to be carried out by considering the rules mentioned in the dedicated manuals. If special equipment is required the service partner has to use it and to ensure the correct function of the tools.

If components and especially soldered components have to be replaced all rules mentioned in dedicated manuals or additional information e.g. service information have to be considered

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GSM Test:

With the availability of the GRT Test /Alignment software, this tool has to be used to perform the outgoing test!

>Connect the mobile/board via internal antenna (antenna coupler) and external antenna (Car cradle/universal antenna clip) to a GSM tester

>Use a Test SIM

For Triple Band phones use a separate test case, if the test software allows only one handover.

Skip the GSM Band test cases if not performed by the mobile phone

Example: 1. Test file Band 1 = GSM900 / Band 2 = GSM1800

2. Test file Band 1 = GSM1900

| est | case | Parameter | Measurements | Limits |
|-----|---|--|--|--------------------|
| 1 | Location Update | • GSM Band 1 • BS Power = -55 dBm • middle BCCH | Display check | • individual check |
| 2 | Call from BS | low TCHhighest PCLBS Power = -75 dBmmiddle BCCH | Ringer/Loudspeaker check | • individual check |
| 3 | TX GSM Band 1 | low TCHhighest PCLBS Power = -75 dBmmiddle BCCH | Frequency Error Phase Error RMS Phase Error Peak Average Power Power Time Template | • GSM Spec. |
| 4 | Handover to GSM Band 2 Including Handover Check | | | |
| 5 | TX GSM Band 2 | • low TCH • highest PCL0 • BS Power = -75 dBm • middle BCCH | Frequency Error Phase Error RMS Phase Error Peak Average Power Power Time Template | GSM Spec. |
| 6 | Call release from BS | | | |

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| Ext | External Antenna | | | | |
|-----|---|---|--|--------------------|--|
| 7 | Call from MS | • GSM900 • high TCH • second highest PCL • BS Power = -75 dBm • middle BCCH | Keyboard check | • individual check | |
| 8 | TX GSM Band 1 | high TCH second highest PCL BS Power = -75 dBm middle BCCH | Frequency Error Phase Error RMS Phase Error Peak Average Power Power Time Template | GSM Spec. | |
| 9 | RX GSM Band 1 | high TCH BS Power = -102 dBm 50 Frames middle BCCH | RX Level RX Qual BER Class Ib BER Class II BER Erased Frames | GSM Spec. | |
| 10 | Handover to GSM Band 2 Including Handover Check | | | | |
| 11 | TX GSM Band 2 | high TCH second highest PCL BS Power = -75 dBm middle BCCH | Frequency Error Phase Error RMS Phase Error Peak Average Power Power Time Template | GSM Spec. | |
| 12 | RX GSM Band2 | • high TCH • BS Power = -102 dBm • 50 Frames • middle BCCH | RX Level RX Qual BER Class Ib BER Class II BER Erased Frames | GSM Spec. | |
| 13 | Call release from MS | | | | |

Final Inspection:

The final inspection contains:

- 1) A 100% network test (location update, and set up call).
- 2) Refer to point 3.3.
- 3) A random sample checks of:
 - Data reset (if required)
 - Optical appearance
 - complete function
- 4) check if PIN-Code is activated (delete the PIN-Code if necessary).

Basis is the international standard of DIN ISO 2859.

Use Normal Sample Plan Level II and the Quality Border 0, 4 for LSO.

Remark: All sample checks must be documented.

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Annex 1

Test SIM Card

There are two different "Test SIM Cards" in use:

1) Test SIM Card from the company "ORGA"

Pin 1 number: 0000 PUK 1 : 12345678

Pin 2 number: 0000 PUK 2 : 23456789

2) Test SIM Card from the company "T-D1"

Pin 1 number: 1234 PUK : 76543210

Pin 2 number: 5678 PUK 2 : 98765432

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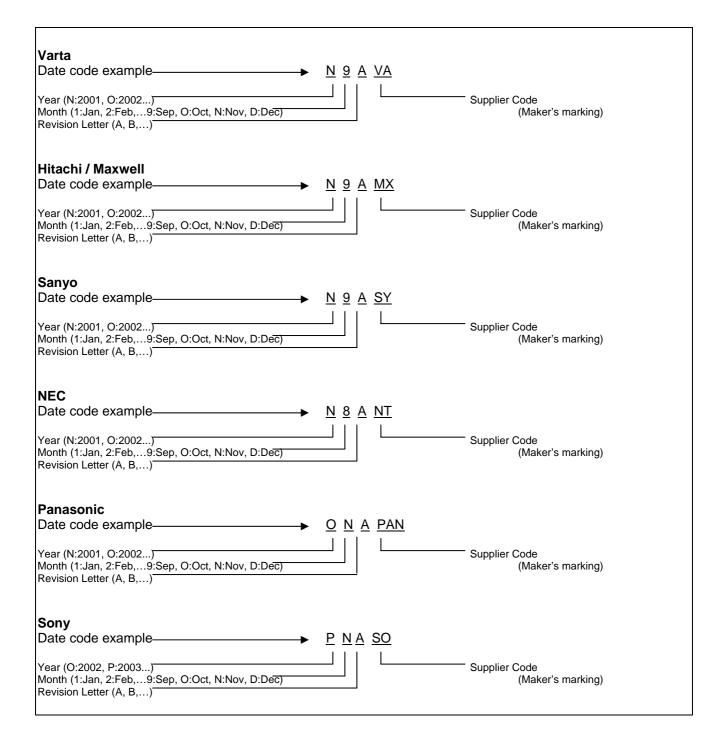
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Annex 2

Battery Date Code overview



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13 Introduction of Service Repair Documentation for Level 3 Basic Repairs – S68

This part of Service Repair Documentation is intended to carry out repairs on BenQ Mobile repair level 3basic (only for workshops without level 3 equipment (special agreement required).

The described failures shall be repaired in BenQ authorized local workshops only.

The level 3basic partners are obliged to send exchanged boards (SWAP) to the next higher Service Repair Partner.

All repairs have to be carried out in an ESD protected environment and with ESD protected equipment/tools. For all activities the international ESD regulations have to be considered.

Assembling/disassembling has to be done according to the latest S68 Level 1-2 repair documentation. It has to be ensured that every repaired mobile Phone is checked according to the latest released General Test Instruction document (both documents are available in the Technical Support section of the C-market).

Check at least weekly C-market for updates and consider all S68 related Customer Care Information

S68 Part number on IMEI label: S30880-S1150-#xxx

, while # may be any letter (A-Z) and xxx may be any number from 100, 101, 102....

Scrap Handling: All Scrap information given in this manual are related to the SCRAP-Rules and instructions.

Attention: Consider the new "LEAD-FREE" soldering rules (available in the communication market), avoid excessive heat.

13.1 Scope

This document is the reference document for all BenQ mobile authorised Service Partners which are released to repair BenQ mobile phones up to level 3 basic.

13.2 Terms and Abbreviations

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14 List of available Level 3 Basic Parts

(According to Component Matrix V1.09 - check C-market for updates)

| Product | ID | Order Number | Description CM |
|---------|-------|-------------------|--------------------------------------|
| S68 | X1400 | L50634-Z97-C467 | CONNECTOR BATTERY 3-POL X85 |
| S68 | X1504 | L50634-Z93-C364 | IO-JACK NANO 12-POL |
| S68 | X1605 | L50634-Z97-C406 | CONNECTOR SIM CARD READER R65 (B) |
| S68 | X2201 | L50697-F5008-F340 | CONNECTOR BOARD TO BOARD 20-POL B |
| S68 | X2705 | L50634-Z97-C363 | CONNECTOR BOARD TO BOARD 14-POL. X75 |
| S68 | Z1601 | L50620-U6029-D670 | FILTER EMI (Fi-Type6) PB Free |

15 Hardware Requirements

(According to L2.5L-L2.5 General soldering information V1.3 - check C-market for updates)

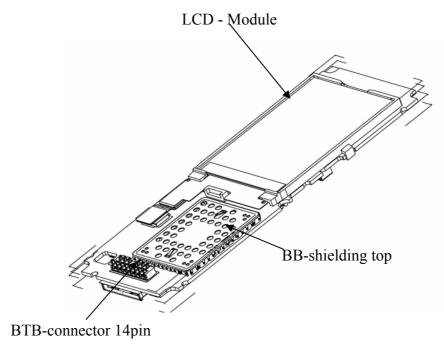
Jigs, Tools and working materials for all described repairs:

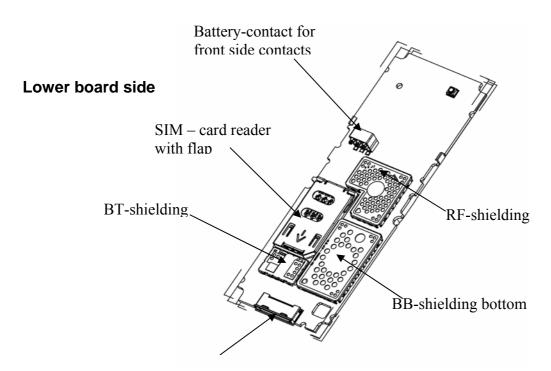
- hot air blower
- soldering gun
- tweezers
- flux
- solder



16 S68 Board Layout

Upper board side





New nano - I/O - connector

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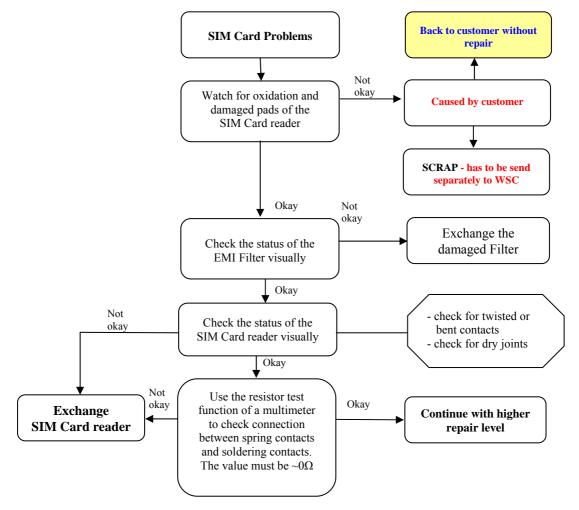
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17 SIM Card Problems

| Fault Symptoms | |
|----------------------------------|-------------------|
| Customer: | GRT: |
| Handset does not accept SIM card | SIM Card Problems |



Connector SIM Card Reader

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C406

E-commerce order name: CONNECTOR SIM CARD READER R65 (B)

Soldering temperature: ~ 360°C TIP Temp.

EMI Filter

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50620-U6029-D670

E-commerce order name: FILTER EMI (Fi-Type6) PB Free

Soldering temperature: ~ 360°C TIP Temp

IRIS Diagnose Code: 43300 Interface/SIM Card reader/Mechanical Damage

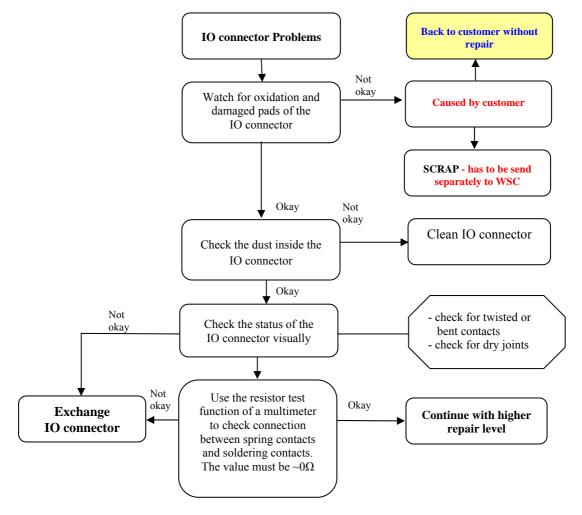
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18 IO Connector Problems

Fault Symptoms Customer: GRT: Charging Problems Problems with external loudspeaker or microphone when using a car kit Problems with accessories connected at the IO connector



Connector IO Jack

Use soldering iron to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z93-C364 E-commerce order name: IO-JACK NANO 12-POL Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 46100 Interface/Charging Connector/Mechanical Damage

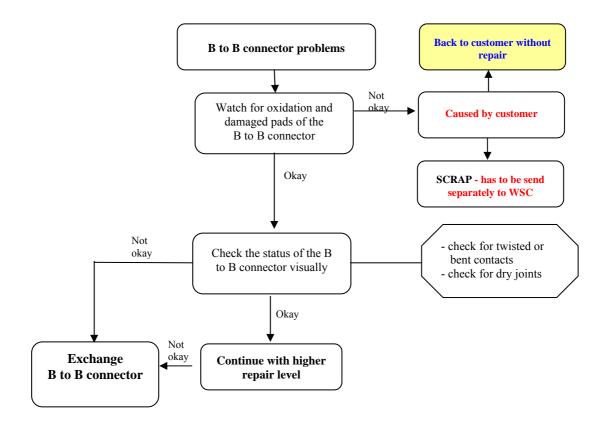
47300 Interface/Data Interface/Mechanical Damage 4B100 Interface/Headset Connector/Mechanical Damage

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19 B to B Connector (upper slider part) Problems

| Fault Symptoms | | |
|--|-------------------------|--|
| Customer: | GRT: | |
| Upper slider keyboard malfunction | Keyboard malfunction | |
| Upper slider keypad illumination does not work | Current measured failed | |
| Display problems | | |



Connector Board to Board

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50697-F5008-F340

L50634-Z97-C363

E-commerce order name: CONNECTOR BOARD TO BOARD 20-POL

CONNECTOR BOARD TO BOARD 14-POL. X75

Soldering temperature: ~ 360°C TIP Temp.

IRIS Diagnose Code: 32200 Keys / Main / Reduced Functionality

36000 Keys / Illumination D TO BOARD 30-POL

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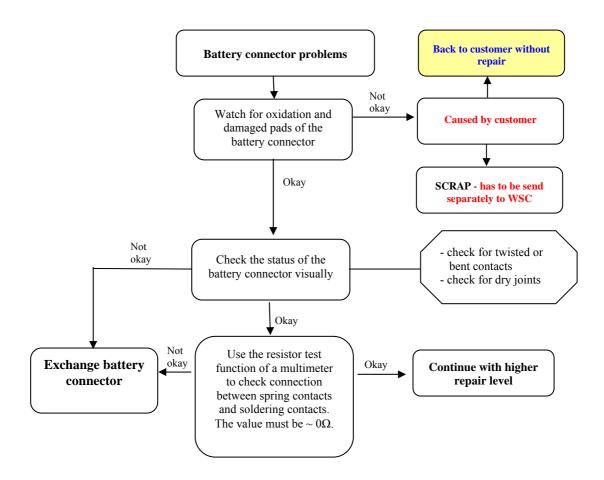
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20 Battery Connector Problems

| Fault Symptoms | |
|---------------------------|----------------------|
| Customer: | GRT: |
| Mobile does not switch on | No connection to GRT |



Connector BATTERY

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50634-Z97-C467

E-Commerce name: CONNECTOR BATTERY 3-POL X85

Soldering temperature: 240 - 255°C

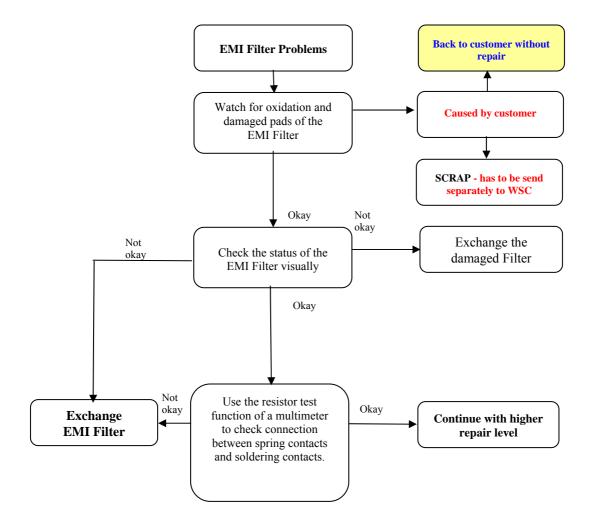
IRIS Diagnose Code: 13000 Battery/Mechanical Damage

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21 Filter EMI Problems

| Fault Symptoms | | |
|---|-----------------------------|--|
| Customer: | GRT: | |
| Handset does not allow data communication via | No service mode possible | |
| I/O connector | No software update possible | |



EMI Filter

Use hot air blower to remove defective component. Avoid excessive heat! Watch surrounding components! Resolder new component afterwards.

E-commerce order number: L50620-U6029-D670 E-commerce order name: FILTER EMI (Fi-Type6) PB Free

Soldering temperature: ~ 360°C TIP Temp

IRIS Diagnose Code: 47000 Data connectivity

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